

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3075965

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	YOUNG HYO KIM	10/20/2014
RECEIVING PARTY DATA		
Name:	SAMSUNG SDI CO., LTD.	
Street Address:	150-20 GONGSE-RO	
Internal Address:	GIHEUNG-GU	
City:	YONGIN-SI	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	446-902	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14520631
CORRESPONDENCE DATA		
Fax Number:	(704)945-6735	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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Correspondent Name:	MELISSA B. PENDLETON	
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ATTORNEY DOCKET NUMBER:	7250.007	
NAME OF SUBMITTER:	MESLISSA B. PENDLETON	
SIGNATURE:	/Melissa B. Pendleton/	
DATE SIGNED:	10/22/2014	
Total Attachments: 4		
source=AssignmentUSPTO#page1.tif		
source=AssignmentUSPTO#page2.tif		
source=AssignmentUSPTO#page3.tif		
source=AssignmentUSPTO#page4.tif		

**RECORDATION FORM COVER SHEET
PATENTS ONLY**

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

YOUNG HYO KIM

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) October 20, 2014

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

2. Name and address of receiving party(ies)

Name: Samsung SDI Co., Ltd.

Internal Address: _____

Street Address: 150-20 Gongse-ro, Giheung-gu

City: Yongin-si

State: Gyeonggi-do

Country: South Korea

Zip: _____

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

14/520,631

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Additon, Higgins & Pendleton, P.A.

Internal Address: _____

Street Address: 11610 N. Community House
Road, Suite 200

City: Charlotte

State: NC Zip: 28277-2199

Phone Number: 704-945-6700

Fax Number: 704-945-6735

Email Address: _____

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ _____

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number _____

Authorized User Name _____

9. Signature: /Melissa B. Pendleton/

October 22, 2014

Signature

Date

Melissa B. Pendleton

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 4

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

ASSIGNMENT

WHEREAS, I, **Young Hyo KIM**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; (hereinafter referred to as "ASSIGNOR"), am the sole inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Thermoplastic Resin Composition Having Excellent Colorability and Mechanical and Physical Properties*, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from a Korean application filed on October 25, 2013, under Serial No. 10-2013-0128137, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Samsung SDI Co., Ltd., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 150-20, Gongse-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-577, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all

continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

October 20, 2014

김영호
Young Hyo KIM